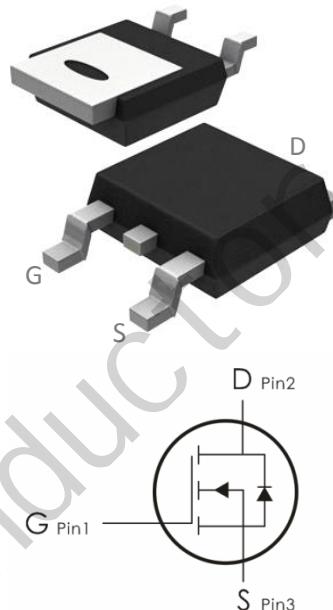


Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.



Features:

- 1) $V_{DS}=100V, I_D=19A, R_{DS(on)} < 60m\Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.

Absolute Maximum Ratings: ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $T_C=25^\circ C$	19	A
	Continuous Drain Current- $T_C=100^\circ C$	12	
	Pulsed Drain Current ¹	70	
P_D	Power Dissipation($T_c=25^\circ C$)	55	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics:

Symbol	Parameter	Max	Units
R_{eJC}	Thermal Resistance,Junction to Case	2.27	°C/W
R_{eJA}	Thermal Resistance,Junction to ambient	62	°C/W

Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	± 100	nA
On Characteristics						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	1.2	1.6	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=5\text{A}$	---	45	60	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=3\text{A}$	---	50	70	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	1680	2150	pF
C_{oss}	Output Capacitance		---	480	700	
C_{rss}	Reverse Transfer Capacitance		---	35	55	
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$V_{\text{DD}}=30\text{V}, I_{\text{D}}=1\text{A}$ $R_{\text{GEN}}=3.3\Omega$	---	2.9	6	ns
t_r	Rise Time ^{2,3}		---	9.5	18	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time ^{2,3}		---	18.4	35	ns
t_f	Fall Time ^{2,3}		---	5.3	10	ns
Q_g	Total Gate Charge ^{2,3}		---	9.3	13	nC
Q_{gs}	Gate-Source Charge ^{2,3}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=48\text{V}, I_{\text{D}}=5\text{A}$	---	2.1	4.2	nC
Q_{gd}	Gate-Drain "Miller" Charge ^{2,3}		---	1.8	4	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A}$	---	---	1	V

Notes:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

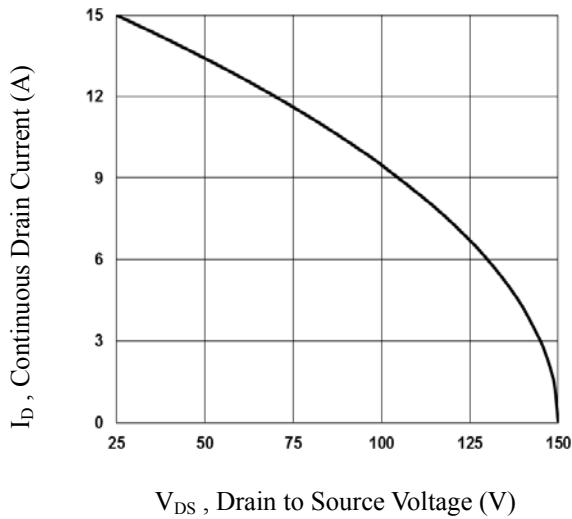
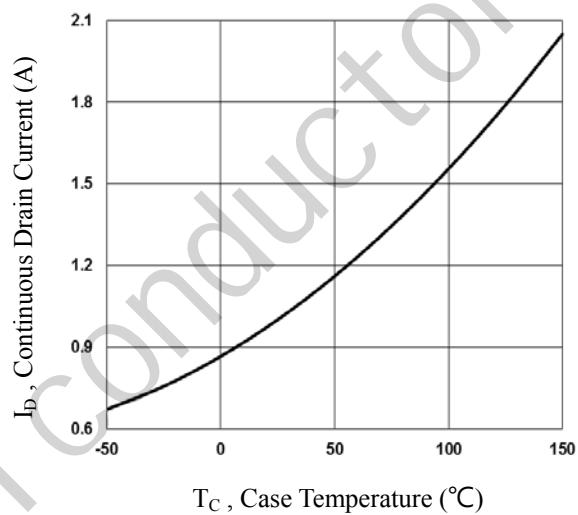
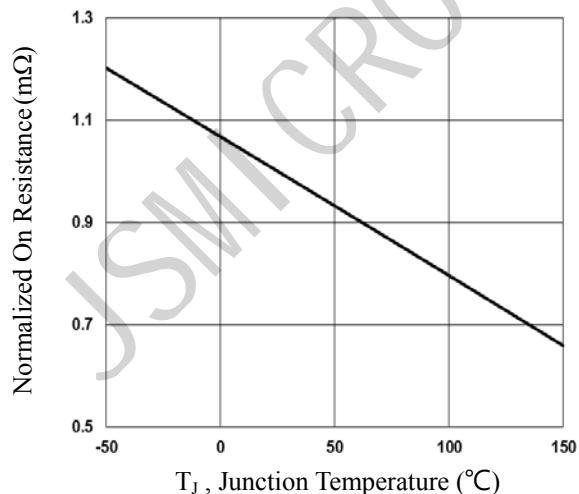
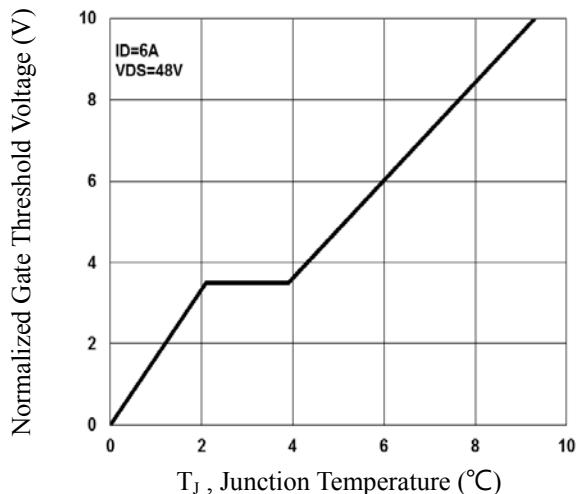
Typical Characteristics: ($T_c=25^\circ C$ unless otherwise noted)


Fig.1 Output Characteristics


 Fig.2 Continuous Drain Current vs. T_c

 Fig.3 Normalized $R_{DS(on)}$ vs. T_j

 Fig.4 Normalized V_{th} vs. T_j

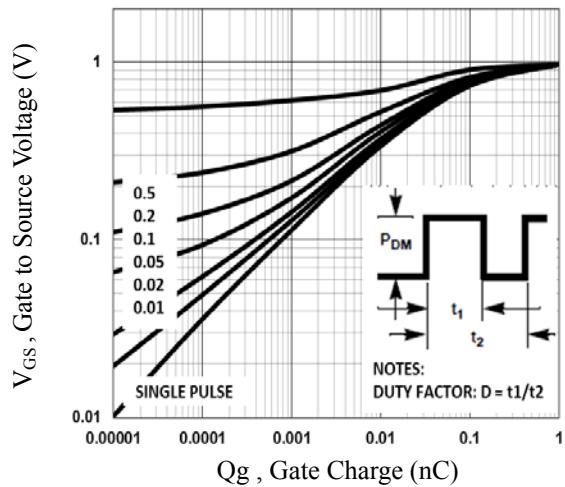


Fig.5 Gate Charge Waveform

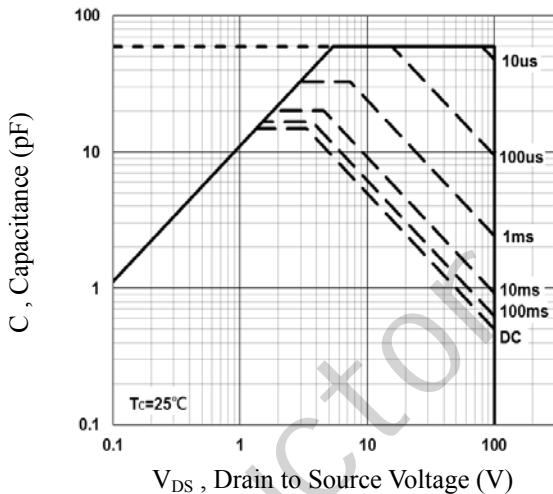


Fig.6 Capacitance Characteristics

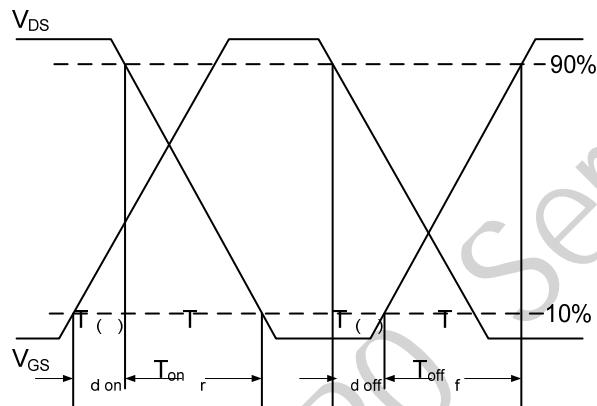


Fig.7 Switching Time Waveform

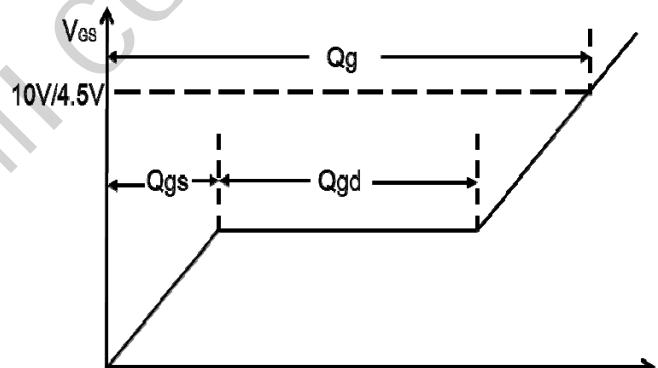


Fig.8 Gate Charge Waveform

外形尺寸图 / Package Dimensions
